



BES2700IHC

Brief Datasheet

Ultra-low Power Bluetooth Audio Platform for TWS Applications with Hybrid ANC

CONTACT US:

Company: Bestechnic (Shanghai) Co., Ltd. (“BES”)

Address: 2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)

Phone: (86)21 6877 1788

For product inquiries and more information, please visit www.bestechnic.com.

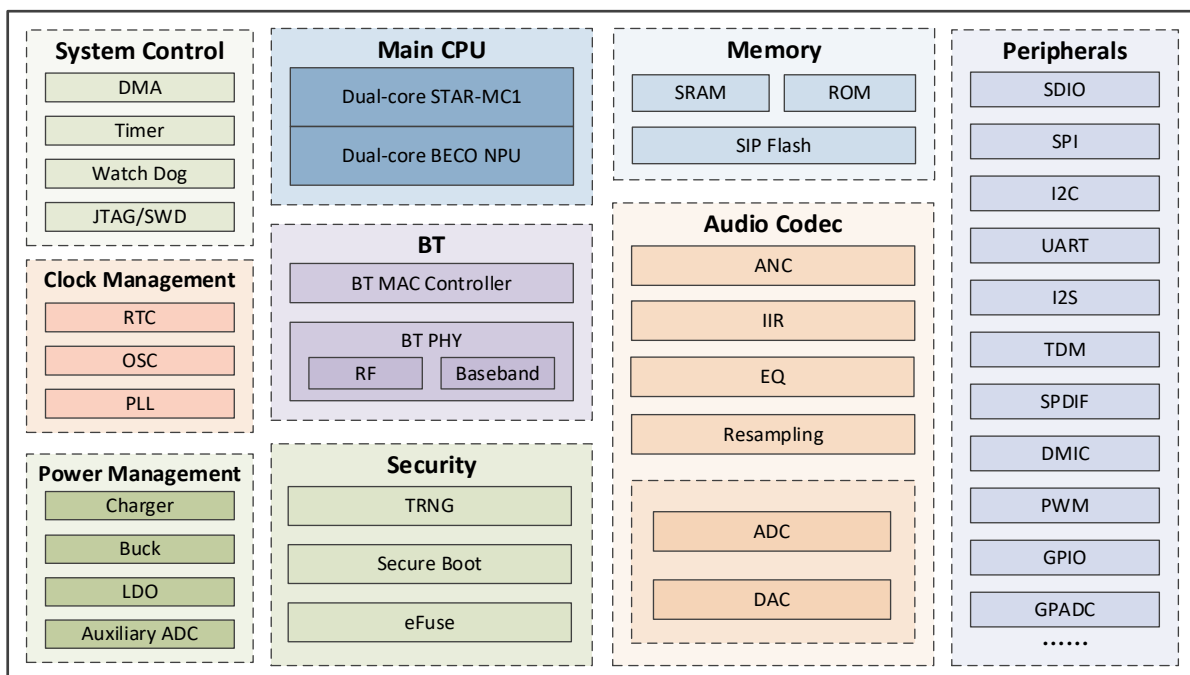
DISCLAIMER:

No part of this document may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, for any purpose, without the express written permission of BES. BES retains the right to make changes to this document at any time, without notice. BES makes no warranty of any kind, expressed or implied, with regard to any information contained in this document, including, but not limited to, the implied warranties of merchant ability or fitness for any particular purpose. Further, BES does not warrant the accuracy or completeness of the information, text, graphics, or other items contained within this document.

1 General Description

The BES2700IHC is an ultra-low power Bluetooth audio SoC. The platform incorporates a CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces. This combination minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem and a Power Management Unit (PMU) with an integrated charger. The highly integrated design is optimized through the use of IBRT technology, a BES patented sniffing technique that incorporates Forward Error Correction (FEC) for enhanced RF performance in TWS systems.



System Block Diagram

1.1 Applications

- TWS earbuds with hybrid ANC
- Stereo Bluetooth headphones/headsets
- Bluetooth speakers
- Other portable audio devices

1.2 Features & Specifications*

CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 512 KB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Audio & Voice Features	2x DACs
	2x ADCs
Peripheral Interfaces	SDIO/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO/GPADC.....
Package	50-pin QFN

* The content in the table is subject to change without notice.